In the Specification:

Please substitute the following paragraphs for the corresponding paragraphs beginning at the indicated location in the specification as originally filed.

Page 10, line 12+:

The device is then completed by provision of suitable insulating, passivation and/or protective layers, preferably in a sequence of layer 80 of TEOS oxide (or, preferably, a silane-based high density plasma oxide), a nitride layer 90 and a polyimide layer 100 which may be photosensitive or not, as desired. A photosensitive polyimide is often preferred, however, when aluminum wiring level 65 includes solder or wire bond pads 105, as shown in Figure 1. A ~~a~~ further titanium nitride layer 70 can also be placed over the aluminum features 65, if desired for enhancement of adhesion to layer 80 or otherwise provide protection or enhancement of conduction characteristics of aluminum features but may be removed in the solder or wire bond areas.

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